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Oct 30, 2018 Delivered the following fixes: 1. Fixed issue where the in game chat was not shown with black background. 2. Fixed issue where the map in the menu did not auto scroll. 3. Fixed issue where there was a delay before the in game chat was shown. 4. Fixed issue where the in game chat was not shown on the map. 5. Fixed issue where the in game chat was not shown. 6. Fixed the issue where the map did not auto scroll. Download Supaplex GO! Sep 15, 2018 Fixed the issue where the sound did not play for the notification. Download Supaplex GO! Jun 18, 2018 Fixed the issue where after loading a chapter the game did not show the graphics for a few seconds. Download Supaplex GO! Jun 17, 2018 Fixed the issue where the device was stopped after loading a chapter. Download Supaplex GO! Jun 12, 2018 Fixed the issue where the device was restarted after loading a chapter. Download Supaplex GO! Feb 16, 2018 Fixed the issue where the application was terminated without user interaction after the in-game character was killed. Download

Supaplex GO! Jan 17, 2018 Fixed the issue where the audio did not play after loading a chapter. Download

Supaplex GO! Jan 15, 2018 Fixed the issue where the in-game photo was not shown. Download

Supaplex GO! Jan 11, 2018 The issue where the device was restarted after loading a chapter has been fixed. Download

Supaplex GO! Dec 5, 2017 Fixed the issue where there was a lag of up to 4 seconds between shots in gameplay mode. Download

Supaplex GO! Dec 5, 2017 Fixed the issue where after downloading the game the cartridge size was not reduced by one. Download

Supaplex GO! Nov 26, 2017 Fixed the issue where you could not see the in-game photo. Download

Supaplex GO! Oct 30, 2017 Fixed the issue where you could not exit the game. Download

Supaplex GO! Aug 5, 2017 Fixed the issue where the map did not auto scroll. Download

Supaplex GO! Aug 4, 2017



Category:Puzzle video games Category:Video games developed in DenmarkThe present invention relates to a printed circuit board and a method of manufacturing a printed circuit board, and more particularly to a technique of preventing solder from being molten in a printed circuit board manufacturing process. A printed circuit board (hereafter referred to as a PCB) includes a single- or multi-layer wiring pattern provided on a surface of a substrate such as an insulating substrate made of an organic material or of an inorganic material, a metal wiring pattern provided on the wiring pattern, and a solder resist covering the wiring pattern and the metal wiring pattern. When manufacturing a PCB, a Cu-solder layer is generally provided as a plated layer on the surface of the substrate and thus a solder resist is provided on the surface of the substrate such that the Cu-solder layer is exposed. In a manufacturing process of a PCB, the surface of the substrate is cleaned. The surface of the substrate to be treated is cleaned by a brush, a sponge or the like. During this cleaning, liquid is also caused to flow onto the surface of the substrate. Therefore, it is desirable that the surface of the substrate be cleaned with the liquid being prevented from dripping or flowing onto portions on which a wiring pattern is not required. This is known as a cleaning process in which liquid is prevented from reaching the wiring pattern. For example, as disclosed in Japanese Laid-Open Patent Publication No. H11-175984, a method of preventing drops of liquid from dripping onto a surface of a substrate to be cleaned before a cleaning process is performed is disclosed. A conventional technique in which a protective tape is attached to the surface of the substrate is also known. For example, as disclosed in Japanese Laid-Open Patent Publication No. 2002-354245, a solder resist is processed after being applied on the surface of the substrate with a protective tape applied in advance thereon. The solder resist is provided on portions on which no electronic components are mounted in order to prevent solder from flowing thereon. In this conventional technique, openings are formed in the protective tape to allow the solder resist to be provided on the portions on which electronic components are mounted. However, there is a problem that the liquid is caused to flow onto portions on which an electronic component is mounted due to the cleaning process before the protective tape is attached to the substrate as described above. This problem is not limited to 82138339de

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